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Substitute for form 1449A/PTO			<p style="text-align: right;"><i>Complete if Known</i></p> <p>Application Number: 10/710,596</p> <p>Filing Date: July 23, 2004</p> <p>First Named Inventor: MOU-SHIUNG LIN</p> <p>Art Unit: 2811</p> <p>Examiner Name: COLLEEN ANN MATTHEWS</p>		
<p>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</p> <p><i>(Use as many sheets as necessary)</i></p>					
Sheet	1	of	3	Attorney Docket No: 085027-0101	

US PATENT DOCUMENTS					
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	1	MISTRY, K. et al. "A 45nm Logic Technology with High-k+ Metal Gate Transistors, Strained Silicon, 9 Cu Interconnect Layers, 193nm Dry Patterning, and 100% Pb-free Packaging," IEEE International Electron Devices Meeting (2007) pgs. 247-250			
	2	EDELSTEIN, D.C., "Advantages of Copper Interconnects," Proceedings of the 12th International IEEE VLSI Multilevel Interconnection Conference (1995) pgs. 301-307			
	3	THENG, C. et al. "An Automated Tool Deployment for ESD (Electro-Static-Discharge) Correct-by-Construction Strategy in 90 nm Process," IEEE International Conference on Semiconductor Electronics (2004) pgs. 61-67			
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	5	YEOH, A. et al. "Copper Die Bumps (First Level Interconnect) and Low-K Dielectrics in 65nm High Volume Manufacturing," Electronic Components and Technology Conference (2006) pgs. 1611-1615			
	6	HU, C-K. et al. "Copper-Polyimide Wiring Technology for VLSI Circuits," Materials Research Society Symposium Proceedings VLSI V (1990) pgs. 369-373			
	7	ROESCH, W. et al. "Cycling copper flip chip interconnects," Microelectronics Reliability, 44 (2004) pgs. 1047-1054			
	8	LEE, Y-H. et al. "Effect of ESD Layout on the Assembly Yield and Reliability," International Electron Devices Meeting (2006) pgs. 1-4			

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	9	YEOH, T-S. "ESD Effects On Power Supply Clamps," Proceedings of the 6th International Symposium on Physical & Failure Analysis of Integrated Circuits (1997) pgs. 121-124	
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	12	JENEI, S. et al. "High Q Inductor Add-on Module in Thick Cu/SiLK™ single damascene," Proceedings from the IEEE International Interconnect Technology Conference (2001) pgs. 107-109	
	13	GROVES, R. et al. "High Q Inductors in a SiGe BiCMOS Process Utilizing a Thick Metal Process Add-on Module," Proceedings of the Bipolar/BiCMOS Circuits and Technology Meeting (1999) pgs. 149-152	
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	15	KUMAR, R. et al. "A Family of 45nm IA Processors," IEEE International Solid-State Circuits Conference, Session 3, Microprocessor Technologies, 3.2 (2009) pgs. 58-59	
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	19	KURD, N. et al. "Next Generation Intel® Micro-architecture (Nehalem) Clocking Architecture," Symposium on VLSI Circuits Digest of Technical Papers (2008) pgs. 62-63	
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	22	LUTHER, B. et al. "Planar Copper-Polyimide Back End of the Line Interconnections for ULSI Devices," Proceedings of the 10th International IEEE VLSI Multilevel Interconnection Conference (1993) pgs. 15-21	
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	25	LIN, M.S. et al. "A New System-on-a-Chip (SOC) Technology – High Q Post Passivation Inductors," Proceedings from the 53rd Electronic Components and Technology Conference (05-30-2003) pgs. 1503-1509	
	26	MEGIC CORP. "MEGIC way to system solutions through bumping and redistribution," (Brochure) (02-06-2004) pgs. 1-3	
	27	LIN, M.S. "Post Passivation Technology™ - MEGIC ® Way to System Solutions," Presentation given at TSMC Technology Symposium, Japan (10-01-2003) pgs. 1-32	
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